

ASD5010

Multi-Mode 8-bit 1000/500/250 MSPS Analog to Digital Converter with Digital Gain

Features

- 8-bit Single/ Dual/ Quad ADC
 - 1 Channel Mode: $F_{Smax} = 1000$ MSPS
 - 2 Channel Mode: $F_{Smax} = 500$ MSPS
 - 4 Channel Mode: $F_{Smax} = 250$ MSPS
- Integrated Cross Point Switches (Mux Array)
- 1X to 50X digital gain. No missing codes up to 32X
- 1X gain: 49.8 dB SNR. 10X gain: 48.2 dB SNR
- Internal low jitter programmable Clock Divider
- Ultra Low Power Dissipation
 - 710 mW including I/O at 1000 MSPS
 - 295 mW including I/O at 500 MSPS and reduced bias
- 0.5 μ s start-up time from Sleep, 15 μ s from Power Down
- Internal reference circuitry with no external components required
- Coarse and fine gain control
- Digital fine gain adjustment for each ADC
- Internal offset correction
- 1.8 V supply voltage
- 1.7 - 3.6 V CMOS logic on control interface pins
- Serial LVDS/RSDS output
- 7mm x 7mm 48 QFN Package

Applications

- USB Powered Oscilloscopes
- Digital Oscilloscopes
- Satellite Receivers

Description

The ASD5010 is a versatile high performance low power analog-to-digital converter (ADC), utilizing time-interleaving to increase sampling rate. Integrated Cross Point Switches activate the input selected by the user.

In single channel mode, one of the four inputs can be selected as valid input to the single ADC channel. In dual channel mode, any two of the four inputs can be selected to each ADC channel. In quad channel mode, any input can be assigned to any ADC channel.

An internal, low jitter and programmable clock divider makes it possible to use a single clock source for all operational modes.

The ASD5010 is based on a proprietary structure, and employs internal reference circuitry, a serial control interface and serial LVDS/RSDS output data. Data and frame synchronization clocks are supplied for data capture at the receiver. Internal 1 to 50X digital coarse gain with ENOB > 7.5 up to 16X gain, allows digital implementation of oscilloscope gain settings. Internal digital fine gain can be set separately for each ADC to calibrate for gain errors.

Various modes and configuration settings can be applied to the ADC through the serial control interface (SPI). Each channel can be powered down independently and data format can be selected through this interface. A full chip idle mode can be set by a single external pin. Register settings determine the exact function of this pin.

ASD5010 is designed to easily interface with Field Programmable Gate Arrays (FPGAs) from several vendors.

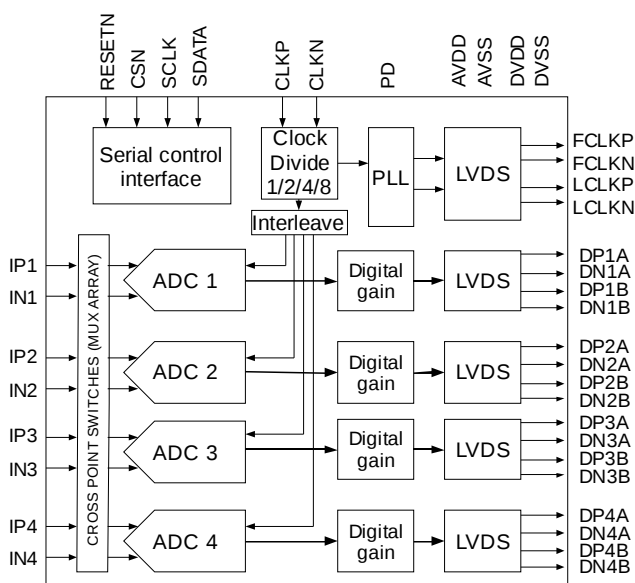


Figure 1: Functional Block Diagram



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Blizzard Product family: Products and Relations

ASD5010 is a part of the ASD Blizzard family of ADCs for Instrumentation applications.

The Blizzard family also includes ASD5020 with two main modes

- High Speed Mode (ASD5020HS): 12-bit up to 640MSPS
- Precision Mode (ASD5020PM): 14-bit up to 105MSPS

Blizzard ADCs are pin compatible. The products within the family can be configured with the SPI interface. The ASD5020 modes can be chosen by SPI configuration. Additionally, ASD5020 can be configured as ASD5010. ASD5010 can not be configured as ASD5020.

This relationship is shown in figure 2

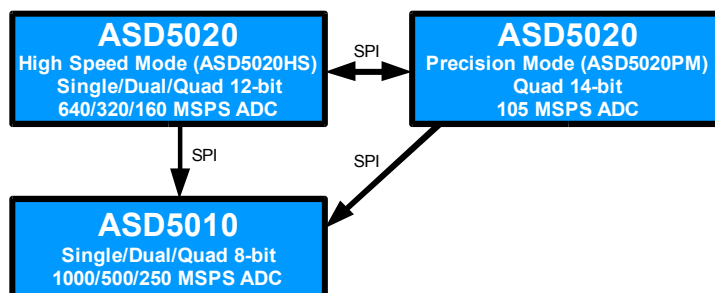


Figure 2: Blizzard Product Family



Specifications

AVDD=1.8V, DVDD=1.8V, OVDD=1.8V, FS = 100 MSPS, Quad Channel Mode, 50% clock duty cycle, -1dBFS 8 MHz input signal, 1x/0dB digital gain (fine and coarse), unless otherwise noted

Parameter	Description	Min	Typ	Max	Unit
DC accuracy					
No missing codes		Guaranteed			
Offset	Offset error after internal digital offset correction		0.05		LSB
G _{abs}	Gain error			±6	%FS
G _{rel}	Gain matching between channels. ±3sigma value at worst case conditions		±0.5		%FS
DNL	Differential non linearity		±0.2		LSB
INL	Integral non linearity		±0.5		LSB
V _{CM,out}	Common mode voltage output		V _{AVDD} /2		
Analog Input					
V _{CM,in}	Analog input common mode voltage	V _{CM} -0.1		V _{CM} +0.2	V
FSR	Differential input voltage full scale range		2.0		V _{pp}
C _{in,Q}	Differential input capacitance, Quad channel mode		5		pF
C _{in,D}	Differential input capacitance, Dual channel mode		7		pF
C _{in,S}	Differential input capacitance, Single channel mode		11		pF
Power Supply					
V _{AVDD}	Analog Supply Voltage	1.7	1.8	2.0	V
V _{DVDD}	Digital and output driver supply voltage	1.7	1.8	2.0	V
V _{OVDD}	Digital CMOS Input Supply Voltage	1.7	1.8	3.6	V
Temperature					
T _A	Operating free-air temperature	-40		85	°C



ASD5010L1000

AVDD=1.8V, DVDD=1.8V, OVDD=1.8V, 50% clock duty cycle, -1dBFS 71 MHz input signal, Gain = 1X, RSDS output data levels unless otherwise noted

Parameter	Description	Min	Typ	Max	Unit
Performance					
SNR	Signal to Noise Ratio, excluding interleaving spurs				
	Single Ch Mode , $F_S = 1000$ MSPS		49.8		dBFS
	Single Ch Mode , $F_S = 1000$ MSPS, $F_{IN} = 170$ MHz		49.7		dBFS
	Single Ch Mode , $F_S = 1000$ MSPS, Gain = 10X		48.2		dBFS
	Single Ch Mode , $F_S = 500$ MSPS		49.8		dBFS
	Single Ch Mode , $F_S = 500$ MSPS, Gain = 10X		48.2		dBFS
	Dual Ch Mode , $F_S = 500$ MSPS		49.8		dBFS
SINAD	Quad Ch Mode , $F_S = 250$ MSPS		49.9		dBFS
	Signal to Noise and Distortion Ratio, including interleaving spurs				
	Single Ch Mode , $F_S = 1000$ MSPS		45.7		dBFS
	Single Ch Mode , $F_S = 1000$ MSPS, $F_{IN} = 170$ MHz		44.2		dBFS
	Single Ch Mode , $F_S = 1000$ MSPS, Gain = 10X		44.5		dBFS
	Single Ch Mode , $F_S = 500$ MSPS		46		dBFS
	Single Ch Mode , $F_S = 500$ MSPS, Gain = 10X		45.4		dBFS
SFDR	Dual Ch Mode , $F_S = 500$ MSPS		44		dBFS
	Quad Ch Mode , $F_S = 250$ MSPS		49.2		dBFS
	Spurious Free Dynamic Range, including interleaving spurs				
	Single Ch Mode , $F_S = 1000$ MSPS		49		dBc
	Single Ch Mode , $F_S = 1000$ MSPS, $F_{IN} = 170$ MHz		48		dBc
	Single Ch Mode , $F_S = 1000$ MSPS, Gain = 10X		50		dBc
	Single Ch Mode , $F_S = 500$ MSPS		49		dBc
SFDR	Single Ch Mode , $F_S = 500$ MSPS, Gain = 10X		49		dBc
	Dual Ch Mode , $F_S = 500$ MSPS		44		dBc
	Quad Ch Mode , $F_S = 250$ MSPS		57		dBc
	Spurious Free Dynamic Range, excluding interleaving spurs				
	Single Ch Mode , $F_S = 1000$ MSPS		64		dBc
	Single Ch Mode , $F_S = 1000$ MSPS, $F_{IN} = 170$ MHz		63		dBc
	Single Ch Mode , $F_S = 1000$ MSPS, Gain = 10X		62		dBc
ENOB	Single Ch Mode , $F_S = 500$ MSPS		67		dBc
	Single Ch Mode , $F_S = 500$ MSPS, Gain = 10X		70		dBc
	Dual Ch Mode , $F_S = 500$ MSPS		64		dBc
	Quad Ch Mode , $F_S = 250$ MSPS		70		dBc
	Effective number of Bits				
	Single Ch Mode , $F_S = 1000$ MSPS		7.3		bits
	Single Ch Mode , $F_S = 1000$ MSPS, $F_{IN} = 170$ MHz		7.0		bits
$X_{tik,2}$	Single Ch Mode , $F_S = 1000$ MSPS, Gain = 10X		7.1		bits
	Single Ch Mode , $F_S = 500$ MSPS		7.3		bits
$X_{tik,4}$	Single Ch Mode , $F_S = 500$ MSPS, Gain = 10X		7.2		bits
	Dual Ch Mode , $F_S = 500$ MSPS		7.0		bits
$X_{tik,4}$	Quad Ch Mode , $F_S = 250$ MSPS		7.9		bits
	CrossTalk Dual Ch Mode. Signal applied to 1 channel (F_{IN0}). Measurement taken on one channel with full scale at F_{IN1} . $F_{IN1} = 8$ MHz, $F_{IN0} = 9.9$ MHz				dBc
Power Supply	CrossTalk Quad Ch Mode. Signal applied to 1 channel (F_{IN0}). Measurement taken on one channel with full scale at F_{IN1} . $F_{IN1} = 8$ MHz, $F_{IN0} = 9.9$ MHz				dBc
	Single Ch: $F_S = 1$ GSPS, Dual Ch: $F_S = 500$ MSPS, Quad Ch: $F_S = 250$ MSPS.				
I_{AVDD}	Analog Supply Current		270		mA



Parameter	Description	Min	Typ	Max	Unit
I _{DVDD}	Digital and output driver Supply Current		125		mA
P _{AVDD}	Analog Power		486		mW
P _{DVDD}	Digital Power		224		mW
P _{TOT}	Total Power Dissipation		710		mW
P _{PD}	Power Down Mode dissipation		15		μW
P _{SLP}	Deep sleep Mode power dissipation		72		mW
P _{SLPCH}	Power dissipation with all channels in sleep channel mode (Light sleep)		153		mW
P _{SLPCH_SAV}	Power dissipation savings per channel off (Quad Channel mode)		139		mW
Analog Input					
FPBW	Full Power Bandwidth		650		MHz
Clock Inputs					
F _{Smax}	Max. Conversion Rate in Modes: Single Ch Dual Ch / Quad Ch	1000 500 / 250			MSPS
F _{Smax}	Min. Conversion Rate in Modes: Single Ch Dual Ch / Quad Ch			120 60 / 30	MSPS



ASD5010L500

AVDD=1.8V, DVDD=1.8V, OVDD=1.8V, 50% clock duty cycle, -1dBFS 70 MHz input signal, Gain = 1X, ADC current scaling -40%, RSDS output data levels unless otherwise noted

Parameter	Description	Min	Typ	Max	Unit
Performance					
SNR	Signal to Noise Ratio, excluding interleaving spurs				
	Single Ch Mode , $F_S = 500$ MSPS		49.9		dBFS
	Single Ch Mode , $F_S = 500$ MSPS, Gain = 10X		48		dBFS
	Dual Ch Mode , $F_S = 250$ MSPS		49.5		dBFS
SINAD	Signal to Noise and Distortion Ratio, including interleaving spurs				
	Single Ch Mode , $F_S = 500$ MSPS		46		dBFS
	Single Ch Mode , $F_S = 500$ MSPS, Gain = 10X		45		dBFS
	Dual Ch Mode , $F_S = 250$ MSPS		49		dBFS
SFDR	Spurious Free Dynamic Range, including interleaving spurs				
	Single Ch Mode , $F_S = 500$ MSPS		49		dBc
	Single Ch Mode , $F_S = 500$ MSPS, Gain = 10X		49		dBc
	Dual Ch Mode , $F_S = 250$ MSPS		59		dBc
SFDR	Spurious Free Dynamic Range, excluding interleaving spurs				
	Single Ch Mode , $F_S = 500$ MSPS		70		dBc
	Single Ch Mode , $F_S = 500$ MSPS, Gain = 10X		70		dBc
	Dual Ch Mode , $F_S = 250$ MSPS		70		dBc
ENOB	Effective number of Bits				
	Single Ch Mode , $F_S = 500$ MSPS		7.3		bits
	Single Ch Mode , $F_S = 500$ MSPS, Gain = 10X		7.2		bits
	Dual Ch Mode , $F_S = 250$ MSPS		7.8		bits
$X_{\text{tik},2}$	CrossTalk Dual Ch Mode. Signal applied to 1 channel ($F_{\text{IN}0}$). Measurement taken on one channel with full scale at $F_{\text{IN}1}$. $F_{\text{IN}1} = 8$ MHz, $F_{\text{IN}0} = 9.9$ MHz				dBc
					dBc
$X_{\text{tik},4}$	CrossTalk Quad Ch Mode. Signal applied to 1 channel ($F_{\text{IN}0}$). Measurement taken on one channel with full scale at $F_{\text{IN}1}$. $F_{\text{IN}1} = 8$ MHz, $F_{\text{IN}0} = 9.9$ MHz				dBc
					dBc
Power Supply					
	Single Ch: $F_S = 500$ MSPS, Dual Ch: $F_S = 250$ MSPS, Quad Ch: $F_S = 125$ MSPS.				
I_{AVDD}	Analog Supply Current		99		mA
I_{DVDD}	Digital and output driver Supply Current		65		mA
P_{AVDD}	Analog Power		178		mW
P_{DVDD}	Digital Power		117		mW
P_{TOT}	Total Power Dissipation		295		mW
P_{PD}	Power Down Mode dissipation		15		μ W
P_{SLP}	Deep sleep Mode power dissipation		49		mW
P_{SLPCH}	Power dissipation with all channels in sleep channel mode (Light sleep)		67		mW
$P_{\text{SLPCH_SAV}}$	Power dissipation savings per channel off (Quad Channel mode)		57		mW
Analog Input					
FPBW	Full Power Bandwidth		500		MHz
Clock Inputs					
F_{Smax}	Max. Conversion Rate in Modes: Single Ch Dual Ch / Quad Ch	500 250 / 125			MSPS
F_{Smin}	Min. Conversion Rate in Modes: Single Ch Dual Ch / Quad Ch			120 60 / 30	MSPS



Digital and Switching Specifications

AVDD=1.8V, DVDD=1.8V, OVDD=1.8V, RSDS output data levels, unless otherwise noted

Parameter	Description	Min	Typ	Max	Unit
Clock Inputs					
DC	Duty Cycle	45		55	% high
Compliance		CMOS, LVDS, LVPECL			
V _{CK,diff}	Differential input voltage swing	+/-200			mVpp
V _{CK,sine}	Differential input voltage swing, sine wave clock input	+/-800			mVpp
V _{CK,CMOS}	Voltage input range CMOS (CLKN connected to ground)		V _{OVDD}		
V _{CM,CK}	Input common mode voltage. Keep voltages within ground and voltage of OVDD	0.3		V _{OVDD} -0.3	V
C _{CK}	Differential Input capacitance		3		pF
Logic inputs (CMOS)					
V _{HI}	High Level Input Voltage. V _{OVDD} ≥ 3.0V	2			V
V _{HI}	High Level Input Voltage. V _{OVDD} = 1.7V – 3.0V	0.8 · V _{OVDD}			V
V _{LI}	Low Level Input Voltage. V _{OVDD} ≥ 3.0V	0		0.8	V
V _{LI}	Low Level Input Voltage. V _{OVDD} = 1.7V – 3.0V	0		0.2 · V _{OVDD}	V
I _{HI}	High Level Input leakage Current			+/-10	μA
I _{LI}	Low Level Input leakage Current			+/-10	μA
C _I	Input Capacitance		3		pF
Data outputs					
Compliance		LVDS / RSDS			
V _{OUT}	Differential output voltage, LVDS		350		mV
V _{OUT}	Differential output voltage, RSDS		150		mV
V _{CM}	Output common mode voltage		1.2		V
Output coding	Default/optional	Offset Binary/ 2's complement			
Timing Characteristics					
t _A	Aperture delay		1.5		ns
t _j	Aperture jitter, One bit set to '1' in jitter_ctrl<7:0>		160		fsrms
T _{skew}	Timing skew between ADC channels		2.5		psrms
T _{SU}	Start up time from Power Down Mode and Deep Sleep Mode to Active Mode in μs. See section "Clock Frequency" for details.		15		μs
T _{SLPCH}	Start up time from Sleep Channel Mode to Active Mode				μs
T _{OVR}	Out of range recovery time		1		clock cycles
T _{LATHSMQ}	Pipeline delay, Quad Channel Mode		32		clock cycles
T _{LATHSMD}	Pipeline delay, Dual Channel Mode		64		clock cycles
T _{LATHSMS}	Pipeline delay, Single Channel Mode		128		clock cycles
LVDS Output Timing Characteristics					
t _{data}	LCLK to data delay time (excluding programmable phase shift)		50		ps
T _{PROP}	Clock propagation delay.	6·T _{LVDS} +2.2	7·T _{LVDS} +3.5	7·T _{LVDS} +5.0	ns
	LVDS bit-clock duty-cycle	45		55	% LCLK cycle
	Frame clock cycle-to-cycle jitter			2.5	% LCLK cycle
T _{EDGE}	Data rise- and fall time 20% to 80%		0.7		ns
T _{CLKEDGE}	Clock rise- and fall time 20% to 80%		0.7		ns



Absolute Maximum Ratings

Applying voltages to the pins beyond those specified in Table 1 could cause permanent damage to the circuit.

Table 1: Maximum voltage ratings

Pin	Reference pin	Rating
AVDD	AVSS	-0.3V to +2.3V
DVDD	DVSS	-0.3V to +2.3V
OVDD	AVSS	-0.3V to +3.9V
AVSS / DVSS	DVSS / AVSS	-0.3V to +0.3V
Analog inputs and outputs	AVSS	-0.3V to +2.3V
CLKx	AVSS	-0.3V to +3.9V
LVDS outputs	DVSS	-0.3V to +2.3V
Digital inputs	DVSS	-0.3V to +3.9V

Table 2 shows the maximum external temperature ratings.

Table 2: Maximum temperature ratings

Operating temperature	-40 to +85 °C
Storage temperature	-60 to +150 °C
Soldering profile qualification	J-STD-020



This device can be damaged by ESD. Even though this product is protected with state-of-the-art ESD protection circuitry, damage may occur if the device is not handled with appropriate precautions. ESD damage may range from device failure to performance degradation. Analog circuitry may be more susceptible to damage as vary small parametric changes can result in specification noncompliance.



Pin Configuration and Description

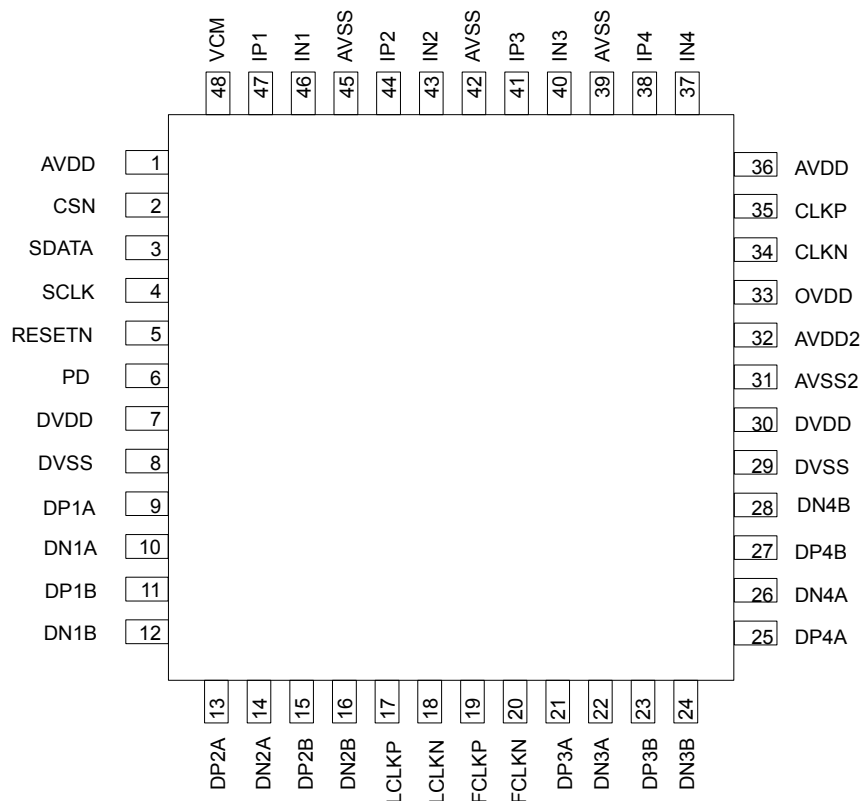


Figure 3: Package diagram

Table 3: Pin descriptions

PIN NAME	DESCRIPTION	PIN NUMBER	# OF PINS
AVDD	Analog power supply, 1.8V	1, 36	2
CSN	Chip select enable. Active low	2	1
SDATA	Serial data input	3	1
SCLK	Serial clock input	4	1
RESETN	Reset SPI interface. Active low	5	1
PD	Power-down input. Activate after applying power in order to initialize the ADC correctly. Alternatively use the SPI power down feature	6	1
DVDD	Digital and I/O power supply, 1.8V	7, 30	2
DVSS	Digital ground	8, 29	2
DP1A	LVDS channel 1A, positive output	9	1
DN1A	LVDS channel 1A, negative output	10	1
DP1B	LVDS channel 1B, positive output	11	1
DN1B	LVDS channel 1B, negative output	12	1
DP2A	LVDS channel 2A, positive output	13	1
DN2A	LVDS channel 2A, negative output	14	1



PIN NAME	DESCRIPTION	PIN NUMBER	# OF PINS
DP2B	LVDS channel 2B, positive output	15	1
DN2B	LVDS channel 2B, negative output	16	1
LCKP	LVDS bit clock, positive output	17	1
LCKN	LVDS bit clock, negative output	18	1
FCLKP	LVDS frame clock (1X), positive output	19	1
FCLKN	LVDS frame clock (1X), negative output	20	1
DP3A	LVDS channel 3A, positive output	21	1
DN3A	LVDS channel 3A, negative output	22	1
DP3B	LVDS channel 3B, positive output	23	1
DN3B	LVDS channel 3B, negative output	24	1
DP4A	LVDS channel 4A, positive output	25	1
DN4A	LVDS channel 4A, negative output	26	1
DP4B	LVDS channel 4B, positive output	27	1
DN4B	LVDS channel 4B, negative output	28	1
AVSS2	Analog ground domain 2	31	1
AVDD2	Analog power supply domain 2, 1.8V	32	1
OVD	Digital CMOS Inputs supply voltage	33	1
CLKN	Negative differential input clock.	34	1
CLKP	Positive differential input clock	35	1
IN4	Negative differential input signal, channel 4	37	1
IP4	Positive differential input signal, channel 4	38	1
AVSS	Analog ground	39, 42, 45	3
IN3	Negative differential input signal, channel 3	40	1
IP3	Positive differential input signal, channel 3	41	1
IN2	Negative differential input signal, channel 2	43	1
IP2	Positive differential input signal, channel 2	44	1
IN1	Negative differential input signal, channel 1	46	1
IP1	Positive differential input signal, channel 1	47	1
VCM	Common mode output pin, 0.5*AVDD	48	1



Start up Initialization

As part of the ASD5010 power-on sequence both a reset and a power down cycle have to be applied to ensure correct start-up initialization. Reset can be done in one of two ways:

1. By applying a low-going pulse (minimum 20 ns) on the RESETN pin (asynchronous).
2. By using the serial interface to set the 'rst' bit high. Internal registers are reset to default values when this bit is set. The 'rst' bit is self-reset to zero. When using this method, do not apply any low-going pulse on the RESETN pin.

Power down cycling can be done in one of two ways:

1. By applying a high-going pulse (minimum 20 ns) on the PD pin (asynchronous).
2. By cycling the 'pd' bit in register 0F_{hex} to high (reg value '0200'_{hex}) and then low (reg value '0000'_{hex}).

Serial Interface

The ASD5010 configuration registers can be accessed through a serial interface formed by the pins SDATA (serial interface data), SCLK (serial interface clock) and CSN (chip select, active low). The following occurs when CSN is set low:

- Serial data are shifted into the chip
- At every rising edge of SCLK, the value present at SDATA is latched
- SDATA is loaded into the register every 24th rising edge of SCLK

Multiples of 24-bit words data can be loaded within a single active CSN pulse. If more than 24 bits are loaded into SDATA during one active CSN pulse, only the first 24 bits are kept. The excess bits are ignored. Every 24-bit word is divided into two parts:

- The first eight bits form the register address
- The remaining 16 bits form the register data

Acceptable SCLK frequencies are from 20MHz down to a few hertz. Duty-cycle does not have to be tightly controlled.

Timing Diagram

Figure 4 shows the timing of the serial port interface. Table 4 explains the timing variables used in figure 4.

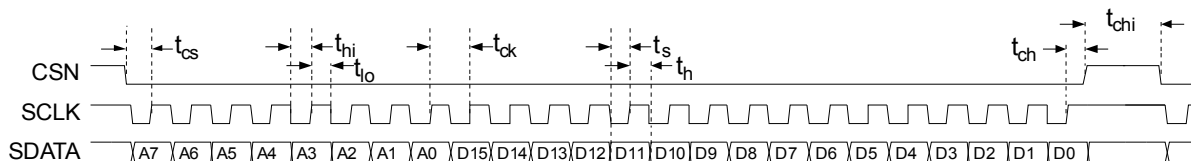


Figure 4: Serial Port Interface timing

Table 4: Serial Port Interface timing definitions

Parameter	Description	Minimum value	Unit
t_{cs}	Setup time between CSN and SCLK	8	ns
t_{ch}	Hold time between CSN and SCLK	8	ns
t_{hi}	SCLK high time	20	ns
t_{lo}	SCLK low time	20	ns
t_{ck}	SCLK period	50	ns
t_s	Data setup time	5	ns
t_h	Data hold time	5	ns



Timing Diagrams

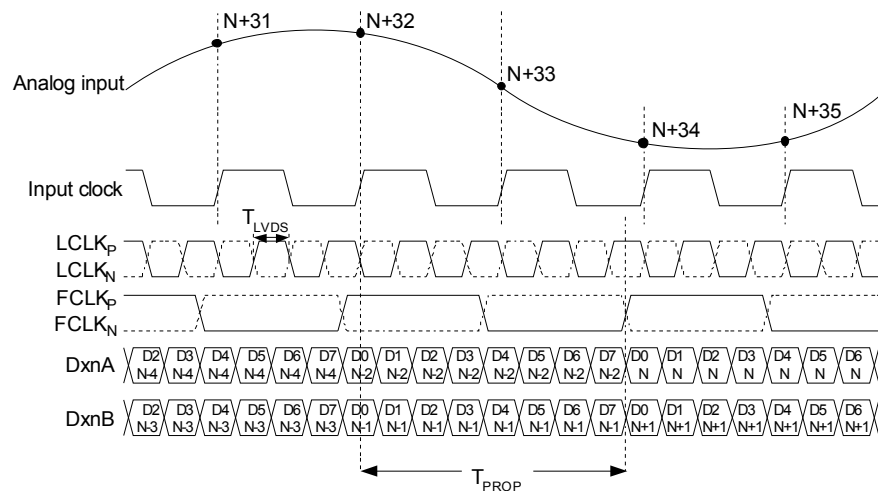


Figure 5: Quad channel - LVDS timing 8-bit output

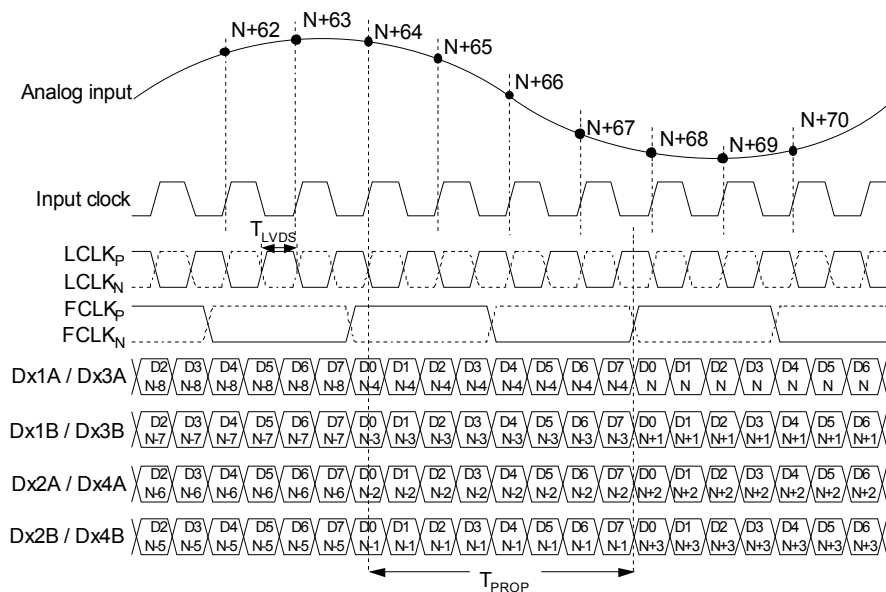


Figure 6: Dual channel - LVDS timing 8-bit output

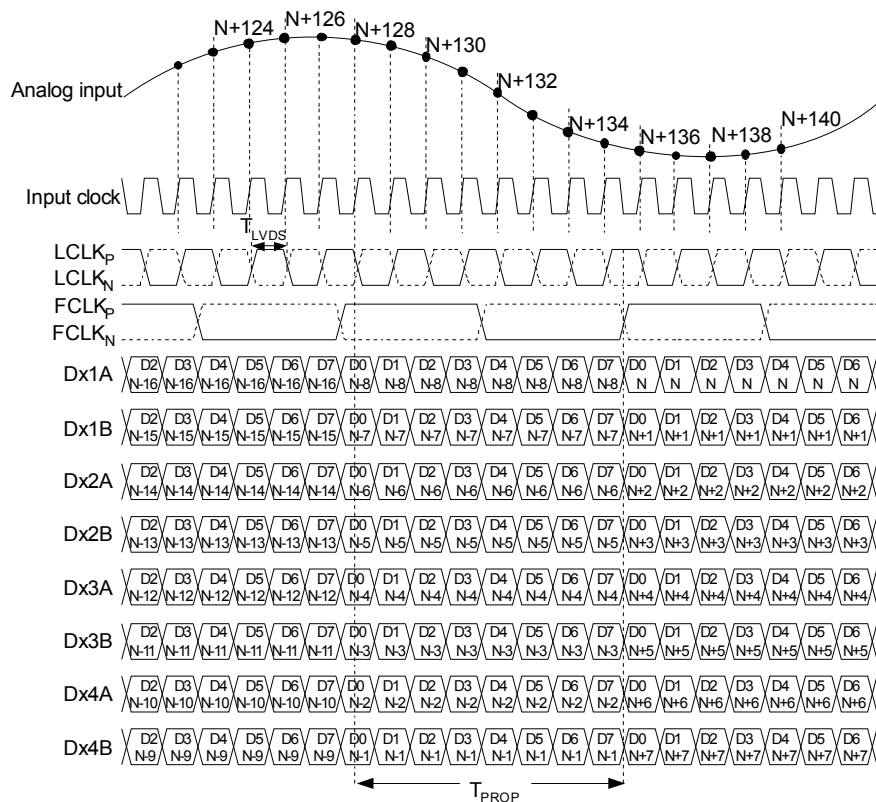


Figure 7: Single channel - LVDS timing 8-bit output

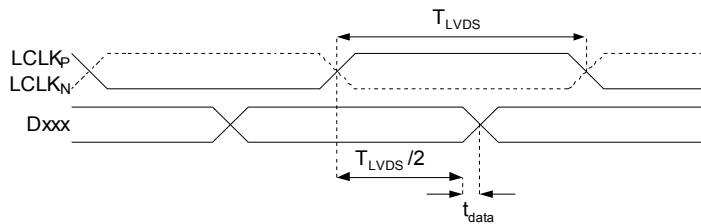


Figure 8: LVDS data timing



Register Map

Table 5: Register map – ASD5010

Name	Description	Default	D15D14D13D12	D11D10D9D8	D7D6D5D4	D3D2D1D0	Hex Address
rst *	Self-clearing software reset.	Inactive				X	0x00
sleep4_ch<4:1>	Channel-specific sleep mode for a Quad Channel setup.	Inactive				X X X X	0x0F
sleep2_ch<2:1>	Channel-specific sleep mode for a Dual Channel setup.	Inactive			X X		
sleep1_ch1	Channel-specific sleep mode for a Single Channel setup.	Inactive			X		
sleep	Go to sleep-mode.	Inactive		X			
pd	Go to power-down.	Inactive		X			
pd_pin_cfg<1:0>	Configures the PD pin function.	PD pin configured for power-down mode		X X			
ilvds_lclk<2:0>	LVDS current drive programmability for LCLKP and LCLKN pins.	3.5 mA drive				X X X	0x11
ilvds_frame<2:0>	LVDS current drive programmability for FCLKP and FCLKN pins.	3.5 mA drive			X X X		
ilvds_dat<2:0>	LVDS current drive programmability for output data pins.	3.5 mA drive		X X X			
en_lvds_term	Enables internal termination for LVDS buffers.	Termination disabled	X				0x12
term_lclk<2:0>	Programmable termination for LCLKN and LCLKP buffers.	Termination disabled	1			X X X	
term_frame<2:0>	Programmable termination for FCLKN and FCLKP buffers.	Termination disabled	1		X X X		
term_dat<2:0>	Programmable termination for output data buffers.	Termination disabled	1	X X X			
invert4_ch<4:1>	Channel specific swapping of the analog input signal for a Quad Channel setup.	IPx is positive input				X X X X	0x24
invert2_ch<2:1>	Channel specific swapping of the analog input signal for a Dual Channel setup.	IPx is positive input			X X		
invert1_ch1	Channel specific swapping of the analog input signal for a Single Channel setup.	IPx is positive input			X		
en_ramp	Enables a repeating full-scale ramp pattern on the outputs.	Inactive			X 0 0		0x25
dual_custom_pat	Enable the mode wherein the output toggles between two defined codes.	Inactive			0 X 0		
single_custom_pat	Enables the mode wherein the output is a constant specified code.	Inactive			0 0 X		
bits_custom1 <7:0>	Bits for the single custom pattern and for the first code of the dual custom pattern.	0x00	X X X X	X X X X			0x26
bits_custom2 <7:0>	Bits for the second code of the dual custom pattern.	0x00	X X X X	X X X X			0x27
cgain4_ch1 <3:0>	Programmable coarse gain channel 1 in a Quad Channel setup.	1x gain				X X X X	0x2A
cgain4_ch2 <3:0>	Programmable coarse gain channel 2 in a Quad Channel setup.	1x gain			X X X X		
cgain4_ch3 <3:0>	Programmable coarse gain channel 3 in a Quad Channel setup.	1x gain		X X X X			
cgain4_ch4 <3:0>	Programmable coarse gain channel 4 in a Quad Channel setup.	1x gain	X X X X				
cgain2_ch1 <3:0>	Programmable coarse gain channel 1 in a Dual Channel setup.	1x gain				X X X X	0x2B
cgain2_ch2 <3:0>	Programmable coarse gain channel 2	1x gain			X X X X		



Name	Description	Default	D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0	Hex Address
cgain1_ch1 <3:0>	in a Dual Channel setup. Programmable coarse gain channel 1 in a Single Channel setup.	1x gain					X	X	X	X									
jitter_ctrl<7:0>	Clock jitter adjustment.	160 fsrms									X	X	X	X	X	X	X	X	0x30
channel_num <2:0> *	Set number of channels: 1, 2 or 4 channels.	4 channels													X	X	X		0x31
clk_divide<1:0>*	Define clock divider factor: 1, 2, 4 or 8	Divide by 1						X	X										
coarse_gain_cfg	Configures the coarse gain setting	x-gain enabled															X		0x33
fine_gain_en	Enable use of fine gain.	Disabled															X		
fgain_branch1<6:0>	Programmable fine gain for branch1.	0dB gain										X	X	X	X	X	X		0x34
fgain_branch2<6:0>	Programmable fine gain for branch 2.	0dB gain	X	X	X		X	X	X	X									
fgain_branch3<6:0>	Programmable fine gain for branch 3.	0dB gain									X	X	X		X	X	X		0x35
fgain_branch4<6:0>	Programmable fine gain for branch 4.	0dB gain	X	X	X		X	X	X	X									
fgain_branch5<6:0>	Programmable fine gain for branch 5.	0dB gain									X	X	X		X	X	X		0x36
fgain_branch6<6:0>	Programmable fine gain for branch 6.	0dB gain	X	X	X		X	X	X	X									
fgain_branch7<6:0>	Programmable fine gain for branch 7.	0dB gain									X	X	X		X	X	X		0x37
fgain_branch8<6:0>	Programmable fine gain for branch 8.	0dB gain	X	X	X		X	X	X	X									
inp_sel_adc1<4:0>	Input select for adc 1.	Signal input: IP1/IN1											X	X	X	X	0		0x3A
inp_sel_adc2<4:0>	Input select for adc 2.	Signal input: IP2/IN2	X	X	X	X	0												
inp_sel_adc3<4:0>	Input select for adc 3.	Signal input: IP3/IN3											X	X	X	X	0		0x3B
inp_sel_adc4<4:0>	Input select for adc 4.	Signal input: IP4/IN4	X	X	X	X	0												
phase_dds<1:0>	Controls the phase of the LCLK output relative to data.	90 degrees									X	X							0x42
pat_deskew	Enable deskew pattern mode.	Inactive														0	X		0x45
pat_sync	Enable sync pattern mode.	Inactive														X	0		
btc_mode	Binary two's complement format for ADC output data.	Straight offset binary													X				0x46
msb_first	Serialized ADC output data comes out with MSB first.	LSB first													X				
adc_curr<2:0>	ADC current scaling.	Nominal														X	X	X	0x50
ext_vcm_bc<1:0>	VCM buffer driving strength control.	Nominal									X	X							
lvds_pd_mode	Controls LVDS power down mode	High z-mode															X		0x52
low_clk_freq *	Low clock frequency used.	Inactive													X	0	0	0	
lvds_advance	Advance LVDS data bits and frame clock by one clock cycle	Inactive									0	X			0	0	0		0x53
lvds_delay	Delay LVDS data bits and frame clock by one clock cycle	Inactive									X	0			0	0	0		
fs_cntrl<5:0>	Fine adjust ADC full scale range	0% change									X	X	X	X	X	X			0x55
startup_ctrl<2:0> *	Controls start-up time.	'000'													X	X	X		0x56

Undefined register addresses must not be written to; incorrect behavior may be the result.

Unused register bits (blank table cells) must be set to '0' when programming the registers.

All registers can be written to while the chip is in power down mode.

*) These registers requires a power down cycle when written to (See Start up Initialization).



Register Description

Software Reset

Name	Description	Default	D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0	Hex Address
rst	Self-clearing software reset.	Inactive															X		0x00

Setting the *rst* register bit to '1', restores the default value of all the internal registers including the *rst* register bit itself.

Modes of Operation and Clock divide factor

Name	Description	Default	D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0	Hex Address
channel_num <2:0>	Set number of channels: 1, 2 or 4 channels.	4 channels													X	X	X		0x31
clk_divide <1:0>	Define clock divider factor: 1, 2, 4 or 8	Divide by 1					X	X											

The ASD5010 has three main operating modes controlled by the register bits *channel_num*<2:0> as defined in table 6. Power down mode, as described in section 'Startup Initialization', must be activated after or during a change of operating mode to ensure correct operation. All active operating modes utilize interleaving to achieve high sampling speed. Quad channel mode interleaves 2 ADC branches, dual channel mode interleaves 4 ADC branches, while single channel mode interleaves all 8 ADC branches.

Table 6: Modes of operation

channel_num <2:0>	Mode of operation	Description
0 0 1	Single channel	Single channel by interleaving ADC1 to ADC4
0 1 0	Dual channel	Dual channel where channel 1 is made by interleaving ADC1 and ADC2, channel 2 by interleaving ADC3 and ADC4
1 0 0	Quad channel	Quad channel where channel 1 corresponds to ADC1, channel2 to ADC2, channel3 to ADC3 and channel 4 to ADC4

Only one of the 3bits should be activated at the same time.

clk_divide<1:0> allows the user to apply an input clock frequency higher than the sampling rate. The clock divider will divide the input clock frequency by a factor of 1, 2, 4, or 8, defined by the *clk_divide*<1:0> register. By setting the *clk_divide*<1:0> value relative to the *channel_num*<2:0> value, the same input clock frequency can be used for all settings on number of channels. e.g: When increasing the number of channels from 1 to 4, the maximum sampling rate is reduced by a factor of 4. By letting *clk_divide*<1:0> follow the *channel_num*<2:0> value, and change it from 1 to 4, the internal clock divider will provide the reduction of the sampling rate without changing the input clock frequency.

Table 7: Clock Divider Factor

clk_divide <1:0>	Clock Divider Factor	Sampling rate (FS)
00 (default)	1	Input clock frequency / 1
01	2	Input clock frequency / 2
10	4	Input clock frequency / 4
11	8	Input clock frequency / 8



Input Select

Name	Description	Default	D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0	Hex Address
inp_sel_adc1<4:0>	Input select for adc 1.	Signal input: IP1/IN1												X	X	X	X	0	0x3A
inp_sel_adc2<4:0>	Input select for adc 2.	Signal input: IP2/IN2		X	X	X	X	0											
inp_sel_adc3<4:0>	Input select for adc 3.	Signal input: IP3/IN3												X	X	X	X	0	0x3B
inp_sel_adc4<4:0>	Input select for adc 4.	Signal input: IP4/IN4		X	X	X	X	0											

Each ADC is connected to the four input signals via a full flexible cross point switch, set up by *inp_sel_adc_x*. In single channel mode, any one of the four inputs can be selected as valid input to the single ADC channel. In dual channel mode, any two of the four inputs can be selected to each ADC channel. In quad channel mode any input can be assigned to any ADC channel. The switching of inputs can be done during normal operation, and no additional actions are needed. The switching will occur instantaneously at the end of each SPI command.

Table 8: ADC input select

inp_sel_adc _x <4:0>	Selected input
0001 0	IP1/IN1
0010 0	IP2/IN2
0100 0	IP3/IN3
1000 0	IP4/IN4
other	Do not use

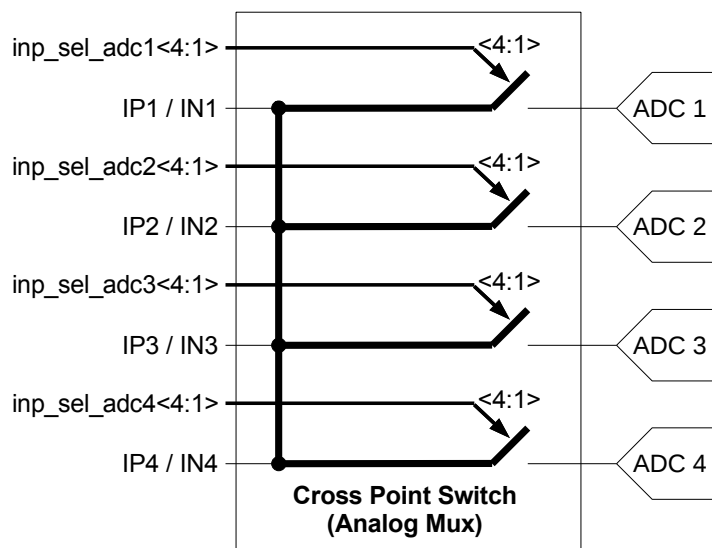


Figure 9: ADC input signals through Cross Point Switch



Full-scale Control

Name	Description	Default	D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0	Hex Address
fs_cntrl<5:0>	Fine adjust ADC full scale range	0% change										X	X	X	X	X	X		0x55

The full-scale voltage range of ASD5010 can be adjusted using an internal 6-bit DAC controlled by the *fs_cntrl* register. Changing the value in the register by one step, adjusts the full-scale range by approximately 0.3%. This leads to a maximum range of ±10% adjustment. Table 9 shows how the register settings correspond to the full-scale range. Note that the values for full-scale range adjustment are approximate. The DAC is, however, guaranteed to be monotonous.

The full-scale control and the programmable gain features differ in two major ways:

1. The full-scale control feature controls the full-scale voltage range in an analog fashion, whereas the programmable gain is a digital feature.
2. The programmable gain feature has much coarser gain steps and larger range than the full-scale control.

Table 9: Register values with corresponding change in full-scale range

fs_cntrl<5:0>	Full-scale range adjustment
111111	+9.7%
111110	+9.4%
...	...
100001	+0.3%
100000	+0%
011111	-0.3%
...	...
000001	-9.7%
000000	-10%

Current Control

Name	Description	Default	D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0	Hex Address
adc_curr<2:0>	ADC current scaling.	Nominal													X	X	X		0x50
ext_vcm_bc<1:0>	VCM buffer driving strength control.	Nominal										X	X						

There are two registers that impact performance and power dissipation.

The *adc_curr* register scales the current consumption in the ADC core. The performance is guaranteed at the nominal setting. Lower power consumption can be achieved by reducing the *adc_curr* value, see table 10. The impact on performance is low for settings down to minimum, but will depend on the ADC sampling rate.

Table 10: ADC current control settings

adc_curr<2:0>	ADC core current
100	-40% (lower performance)
101	-30%
110	-20%
111	-10%
000 (default)	Nominal
001	Do not use
010	Do not use
011	Do not use



The `ext_vcm_bc` register controls the driving strength in the buffer supplying the voltage on the VCM pin. If this pin is not in use, the buffer can be switched off. If current is drawn from the VCM pin, the driving strength can be increased to keep the voltage on this pin at the correct level.

Table 11: External common mode voltage buffer driving strength

<code>ext_vcm_bc<1:0></code>	VCM buffer driving strength [μA] Max current sinked/sourced from VCM pin with < 20 mV voltage change.
00	Off (VCM floating)
01 (default)	+/-20
10	+/-400
11	+/-700



Start-up and Clock Jitter Control

Name	Description	Default	D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0	Hex Address
startup_ctrl<2:0>	Controls start-up time.	'000'													X	X	X		0x56
jitter_ctrl<7:0>	Clock jitter adjustment.	160 fsrms									X	X	X	X	X	X	X	X	0x30

To optimize start up time, a register is provided where the start-up time in number of clock cycles can be set. Some internal circuitry have start up times that are clock frequency independent. Default counter values are set to accommodate these start up times at the maximum clock frequency (sampling rate). This will lead to increased start up times at low clock frequencies. Setting the value of this register to the nearest higher clock frequency will reduce the count values of the internal counters, to better fit the actual start up time, such that the start up time will be reduced. The start up times from power down and sleep modes are changed by this register setting. If the clock divider is used (set to other than 1), the input clock frequency must be divided by the divider factor to find the correct clock frequency range (see table 7).

Table 12: Start-up time control settings

Quad channel				Dual channel			
startup_ctrl<2:0>	Clock frequency range [MSPS]	Startup delay [clock cycles]	Startup delay [μs]	startup_ctrl<2:0>	Clock frequency range [MSPS]	Startup delay [clock cycles]	Startup delay [μs]
100	160 - 250	3072	12.3 – 19.2	100	320 - 500	6144	12.3 – 19.2
000	100 - 160	1984	12.4 - 19.8	000	200 - 320	3968	12.4 - 19.8
001	65 - 100	1280	12.8 - 19.7	001	130 – 200	2560	12.8 - 19.7
010	40 - 65	840	12.9 - 21	010	80 - 130	1680	12.9 - 21
011	30 - 40	520	13 - 17.3	011	60 – 80	1040	13 - 17.3
other	Do not use	-	-	other	Do not use	-	-

Single channel			
startup_ctrl<2:0>	Clock frequency range [MSPS]	Startup delay [clock cycles]	Startup delay [μs]
100	640 - 1000	12288	12.3 – 19.2
000	400 - 640	7936	12.4 - 19.8
001	260 - 400	5120	12.8 - 19.7
010	160 - 260	3360	12.9 - 21
011	120 - 160	2080	13 - 17.3
other	Do not use	-	-

jitter_ctrl<7:0> allows the user to set a trade-off between power consumption and clock jitter. If all bits in the register is set low, the clock signal is stopped. The clock jitter depends on the number of bits set to '1' in the jitter_ctrl<7:0> register. Which bits are set high does not affect the result.



Table 13: Clock jitter performance

Number of bits to '1' in jitter_ctrl<7:0>	Clock jitter performance	Module current consumption
	[fsrms]	[mA]
1	160	1
2	150	2
3	136	3
4	130	4
5	126	5
6	124	6
7	122	7
8	120	8
0	Clock stopped	



LVDS Output Configuration and Control

Name	Description	Default	D15D14D13D12	D11D10D9D8	D7D6D5D4	D3D2D1D0	Hex Address
low_clk_freq	Low clock frequency used.	Inactive				X 0 0 0	
lvds_advance	Advance LVDS data bits and frame clock by one clock cycle	Inactive			0 X	0 0 0	0x53
lvds_delay	Delay LVDS data bits and frame clock by one clock cycle	Inactive			X 0	0 0 0	
phase_ddr<1:0>	Controls the phase of the LCLK output relative to data.	90 degrees			X X		0x42
btc_mode	Binary two's complement format for ADC output data.	Straight offset binary				X	
msb_first	Serialized ADC output data comes out with MSB first.	LSB first				X	0x46

The ASD5010 uses an 8-bit serial LVDS output interface as shown in the Timing Diagrams section. The different selection of number of channels uses the LVDS outputs as defined by table 14.

Table 14: Use of LVDS outputs

Channel set-up	LVDS outputs used
Single channel	D1A, D1B, D2A, D2B, D3A, D3B, D4A, D4B
Dual channel, channel 1	D1A, D1B, D2A, D2B
Dual channel, channel 2	D3A, D3B, D4A, D4B
Quad channel, channel 1	D1A, D1B
Quad channel, channel 2	D2A, D2B
Quad channel, channel 3	D3A, D3B
Quad channel, channel 4	D4A, D4B

Maximum data output bit-rate for ASD5010L1000 is 1 Gb/s and for ASD5010L500 500Mb/s. The maximum sampling rate for the different configurations is given by table 15. The sampling rate is set by the frequency of the input clock (F_S). The frame-rate, i.e. the frequency of the FCLK signal on the LVDS outputs, depends on the selected mode and the sampling frequency (F_S) as defined in table 26.

Table 15: Maximum sampling rate for different ASD5010 configurations

Product	Single channel [MSPS]	Dual channel [MSPS]	Quad channel [MSPS]
ASD5010L1000	1000	500	250
ASD5010L500	500	250	125

Table 16: Output data frame rate

Mode of operation	Frame-rate (FCLK frequency)
Single channel	$F_S / 8$
Dual channel	$F_S / 4$
Quad channel	$F_S / 2$

If the ASD5010 device is used at a low sampling rate the register bit *low_clk_freq* has to be set to '1'. See table 17 for when to use this register bit for the different modes of operation.



Table 17: Use of register bit *low_clk_freq*

Mode of operation	Limit when <i>low_clk_freq</i> should be activated
Single channel	$F_S < 240 \text{ MHz}$
Dual channel	$F_S < 120 \text{ MHz}$
Quad channel	$F_S < 60 \text{ MHz}$

To ease timing in the receiver when using multiple ASD5010, the device has the option to adjust the timing of the output data and the frame clock. The propagation delay with respect to the ADC input clock can be moved one LVDS clock cycle forward or backward, by using *lvds_delay* and *lvds_advance*, respectively. See figure 10 for details. Note that LCLK is not affected by *lvds_delay* or *lvds_advance* settings.

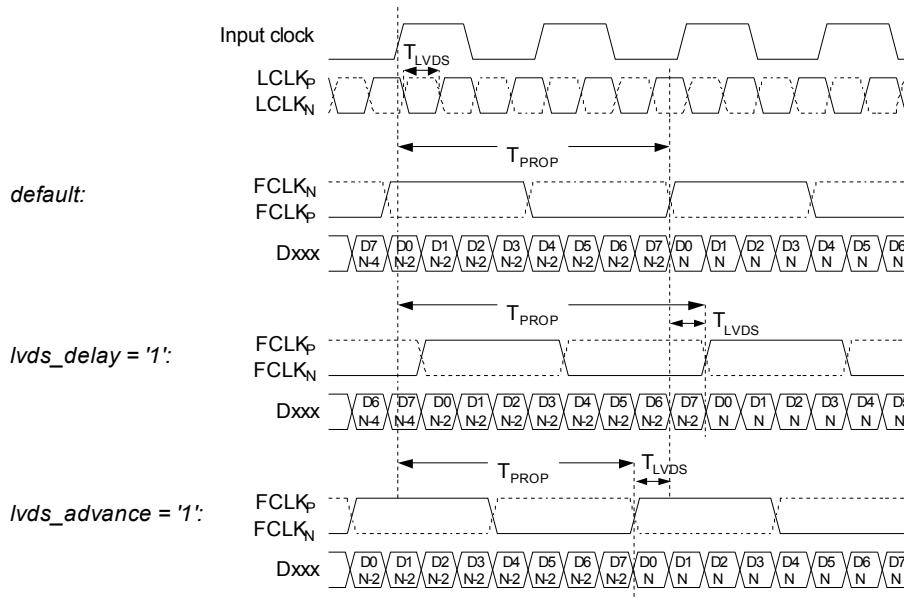


Figure 10: LVDS output timing adjustment

The LVDS output interface of ASD5010 is a DDR interface. The default setting is with the LCLK rising and falling edge transitions in the middle of alternate data windows. The phase for LCLK can be programmed relative to the output frame clock and data bits using *phase_ddr<1:0>*. The LCLK phase modes are shown in figure 11. The default timing is identical to setting *phase_ddr<1:0>='10'*.

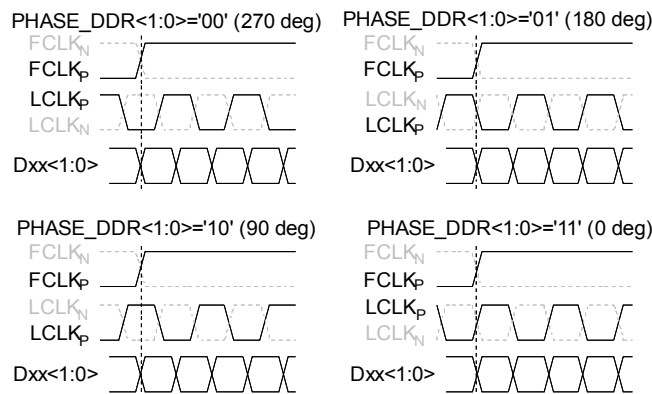


Figure 11: Phase programmability modes for LCLK



The default data output format is offset binary. Two's complement mode can be selected by setting the *btc_mode* bit to '1' which inverts the MSB.

The first bit of the frame (following the rising edge of FCLKP) is the LSB of the ADC output for default settings. Programming the *msb_first* mode results in reverse bit order, and the MSB is output as the first bit following the FCLKP rising edge.

LVDS Drive Strength Programmability

Name	Description	Default	D15D14D13D12	D11D10D9D8	D7D6D5D4	D3D2D1D0	Hex Address
<i>ilvds_lclk</i> <2:0>	LVDS current drive programmability for LCLKP and LCLKN pins.	3.5 mA drive				X X X	0x11
<i>ilvds_frame</i> <2:0>	LVDS current drive programmability for FCLKP and FCLKN pins.	3.5 mA drive			X X X		
<i>ilvds_dat</i> <2:0>	LVDS current drive programmability for output data pins.	3.5 mA drive		X X X			

The current delivered by the LVDS output drivers can be configured as shown in table 18. The default current is 3.5mA, which is what the LVDS standard specifies.

To reduce power consumption in the ASD5010, Reduced Swing Data Signaling (RSDS), is recommended. The output current drive setting should then be 1.5 mA.

Setting the *ilvds_lclk*<2:0> register controls the current drive strength of the LVDS clock output on the LCLKP and LCLKN pins.

Setting the *ilvds_frame*<2:0> register controls the current drive strength of the frame clock output on the FCLKP and FCLKN pins.

Setting the *ilvds_dat*<2:0> register controls the current drive strength of the data outputs on the D[8:1]P and D[8:1]N pins.

Table 18: LVDS output drive strength for LCLK, FCLK and data

<i>ilvds_*</i> <2:0>	LVDS drive strength
000	3.5 mA (default)
001	2.5 mA
010	1.5 mA (RSDS)
011	0.5 mA
100	7.5 mA
101	6.5 mA
110	5.5 mA
111	4.5 mA

LVDS Internal Termination Programmability

Name	Description	Default	D15D14D13D12	D11D10D9D8	D7D6D5D4	D3D2D1D0	Hex Address
<i>en_lvds_term</i>	Enables internal termination for LVDS buffers.	Termination disabled	X				0x12
<i>term_lclk</i> <2:0>	Programmable termination for LCLKN and LCLKP buffers.	Termination disabled	1			X X X	
<i>term_frame</i> <2:0>	Programmable termination for FCLKN and FCLKP buffers.	Termination disabled	1		X X X		
<i>term_dat</i> <2:0>	Programmable termination for output data buffers.	Termination disabled	1	X X X			

The off-chip load on the LVDS buffers may represent a characteristic impedance that is not perfectly matched with the



PCB traces. This may result in reflections back to the LVDS outputs and loss of signal integrity. This effect can be mitigated by enabling an internal termination between the positive and negative outputs of each LVDS buffer. Internal termination mode can be selected by setting the *en_lvds_term* bit to '1'. Once this bit is set, the internal termination values for the bit clock, frame clock, and data buffers can be independently programmed using sets of three bits. Table 19 shows how the internal termination of the LVDS buffers are programmed. The values are typical values and can vary by up to $\pm 20\%$ from device to device and across temperature.

Table 19: LVDS output internal termination for LCLK, FCLK and data

term_ *<2:0>	LVDS Internal Termination
000	Termination disabled
001	260 Ω
010	150 Ω
011	94 Ω
100	125 Ω
101	80 Ω
110	66 Ω
111	55 Ω



Power Mode Control

Name	Description	Default	D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0	Hex Address
sleep4_ch<4:1>	Channel-specific sleep mode for a Quad Channel setup.	Inactive													X	X	X	X	0x0F
sleep2_ch<2:1>	Channel-specific sleep mode for a Dual Channel setup.	Inactive											X	X					
sleep1_ch1	Channel-specific sleep mode for a Single Channel setup.	Inactive										X							
sleep	Go to sleep-mode.	Inactive							X										
pd	Go to power-down.	Inactive						X											
pd_pin_cfg<1:0>	Configures the PD pin function.	PD pin configured for power-down mode					X	X											
lvds_pd_mode	Controls LVDS power down mode	High z-mode															X	0x52	

The ASD5010 device has several modes for power management, from sleep modes with short start up time to full power down with extremely low power dissipation. There are two sleep modes, both with the LVDS clocks (FCLK, LCLK) running, such that the synchronization with the receiver is maintained. The first is a light sleep mode (*sleep*_ch*) with short start up time, and the second a deep sleep mode (*sleep*) with the same start up time as full power down.

Setting *sleep4_ch<n>* = '1' sets channel <n> in a Quad Channel setup in sleep mode. Setting *sleep2_ch<n>* = '1' sets channel <n> in a Dual Channel setup in sleep mode. Setting *sleep1_ch1* = '1' sets the ADC channel in a Single Channel setup in sleep mode. This is a light sleep mode with short start up time.

Setting *sleep* = '1', puts all channels to sleep, but keeps FCLK and LCLK running to maintain LVDS synchronization. The start up time is the same as for complete power down. Power consumption is significantly lower than for setting all channels to sleep by using the *sleep*_ch* register.

Setting *pd* = '1' completely powers down the chip, including the band-gap reference circuit. Start-up time from this mode is significantly longer than from the *sleep*_ch* mode. The synchronization with the LVDS receiver is lost since LCLK and FCLK outputs are put in high-Z mode.

Setting *pdn_pin_cfg<1:0>* = 'x1' configures the circuit to enter sleep channel mode (all channels off) when the PD pin is set high. This is equal to setting all channels to sleep by using *sleep*_ch*. The channels can not be powered down separately using the PD pin. Setting *pdn_pin_cfg<1:0>* = '10' configures the circuit to enter (deep) sleep mode when the PD pin is set high (equal to setting *sleep*='1'). When *pdn_pin_cfg <1:0>* = '00', which is the default, the circuit enters the power down mode when the PD pin is set high.

The *lvds_pd_mode* register configures whether the LVDS data output drivers are powered down or kept alive in sleep and sleep channel modes. LCLK and FCLK drivers are not affected by this register, and are always on in sleep and sleep channel modes. If *lvds_pd_mode* is set low (default), the LVDS output is put in high Z mode, and the driver is completely powered down. If *lvds_pd_mode* is set high, the LVDS output is set to constant 0, and the driver is still on during sleep and sleep channel modes.



Programmable Gain

Name	Description	Default	D15D14D13D12	D11D10D9D8	D7D6D5D4	D3D2D1D0	Hex Address
cgain_cfg	Configures the coarse gain setting	x-gain enabled				X	0x33
fine_gain_en	Enable use of fine gain.	Disabled				X	
cgain4_ch1 <3:0>	Programmable coarse gain channel 1 in a Quad Channel setup.	1x gain				X X X X	0x2A
cgain4_ch2 <3:0>	Programmable coarse gain channel 2 in a Quad Channel setup.	1x gain			X X X X		
cgain4_ch3 <3:0>	Programmable coarse gain channel 3 in a Quad Channel setup.	1x gain		X X X X			
cgain4_ch4 <3:0>	Programmable coarse gain channel 4 in a Quad Channel setup.	1x gain	X X X X				
cgain2_ch1 <3:0>	Programmable coarse gain channel 1 in a Dual Channel setup.	1x gain				X X X X	0x2B
cgain2_ch2 <3:0>	Programmable coarse gain channel 2 in a Dual Channel setup.	1x gain			X X X X		
cgain1_ch1 <3:0>	Programmable coarse gain channel 1 in a 1 channel setup.	1x gain		X X X X			
fgain_branch1<6:0>	Programmable fine gain for branch 1.	0dB gain			X X X	X X X X	0x34
fgain_branch2<6:0>	Programmable fine gain for branch 2.	0dB gain	X X X	X X X X			
fgain_branch3<6:0>	Programmable fine gain for branch 3.	0dB gain			X X X	X X X X	0x35
fgain_branch4<6:0>	Programmable fine gain for branch 4.	0dB gain	X X X	X X X X			
fgain_branch5<6:0>	Programmable fine gain for branch 5.	0dB gain			X X X	X X X X	0x36
fgain_branch6<6:0>	Programmable fine gain for branch 6.	0dB gain	X X X	X X X X			
fgain_branch7<6:0>	Programmable fine gain for branch 7.	0dB gain			X X X	X X X X	0x37
fgain_branch8<6:0>	Programmable fine gain for branch 8.	0dB gain	X X X	X X X X			

The device includes a digital programmable gain in addition to the Full-scale control. The programmable gain of each channel can be individually set using a four bit code, indicated as *cgain**<3:0>. The gain is configured by the register *cgain_cfg*, when *cgain_cfg* equals '0' a gain in dB steps is enabled as defined in table 20 otherwise if *cgain_cfg* equals '1' the gain is defined by table 21. There will be no missing codes for gain settings lower than 32x (30dB), due to higher than 8 bit resolution internally.

Table 20: Gain setting – dB step

cgain_cfg	cgain*<3:0>	Implemented gain [dB]
0	0000	0
0	0001	1
0	0010	2
0	0011	3
0	0100	4
0	0101	5
0	0110	6
0	0111	7
0	1000	8
0	1001	9
0	1010	10
0	1011	11
0	1100	12
0	1101	Not used
0	1110	Not used
0	1111	Not used



Table 21: Gain setting - x step

cgain_cfg	cgain* <3:0>	Implemented gain factor [x]
1	0000	1
1	0001	1.25
1	0010	2
1	0011	2.5
1	0100	4
1	0101	5
1	0110	8
1	0111	10
1	1000	12.5
1	1001	16
1	1010	20
1	1011	25
1	1100	32
1	1101	50
1	1110	Not used
1	1111	Not used

There is a digital fine gain implemented for each ADC to adjust the fine gain errors between the ADCs. The gain is controlled by *fgain_branch** as defined in table 22. There will be no missing codes when using digital fine gain, due to higher resolution internally.

To enable the fine gain function the register bit *fine_gain_en* has to be activated, set to '1'.

Table 22: Fine gain setting

fgain_branchx <6:0>	Arithmetic function	Implemented gain (x)	Gain (dB)
0 1 1 1 1 1 1	$OUT=(1+2^{-8}+2^{-9}+2^{-10}+2^{-11}+2^{-12}+2^{-13})\cdot IN$	1.0077	0.0665
0 1 1 1 1 1 0	$OUT=(1+2^{-8}+2^{-9}+2^{-10}+2^{-11}+2^{-12})\cdot IN$	1.0076	0.0655
0 1 1 1 1 0 1	$OUT=(1+2^{-8}+2^{-9}+2^{-10}+2^{-11}+2^{-13})\cdot IN$	1.0074	0.0644
0 1 1 1 1 0 0	$OUT=(1+2^{-8}+2^{-9}+2^{-10}+2^{-11})\cdot IN$	1.0073	0.0634
...
0 0 0 0 0 1 1	$OUT=(1+2^{-12}+2^{-13})\cdot IN$	1.0004	0.0031
0 0 0 0 0 1 0	$OUT=(1+2^{-12})\cdot IN$	1.0002	0.0021
0 0 0 0 0 0 1	$OUT=(1+2^{-13})\cdot IN$	1.0001	0.0010
0 0 0 0 0 0 0	$OUT=IN$	1.0000	0.0000
1 1 1 1 1 1 1	$OUT=IN$	1.0000	0.0000
1 1 1 1 1 1 0	$OUT=(1-2^{-13})\cdot IN$	0.9999	-0.0011
1 1 1 1 1 0 1	$OUT=(1-2^{-12})\cdot IN$	0.9998	-0.0021
1 1 1 1 1 0 0	$OUT=(1-2^{-12}-2^{-13})\cdot IN$	0.9996	-0.0032
...
1 0 0 0 0 1 1	$OUT=(1-2^{-8}-2^{-9}-2^{-10}-2^{-11})\cdot IN$	0.9927	-0.0639
1 0 0 0 0 1 0	$OUT=(1-2^{-8}-2^{-9}-2^{-10}-2^{-11}-2^{-13})\cdot IN$	0.9926	-0.0649
1 0 0 0 0 0 1	$OUT=(1-2^{-8}-2^{-9}-2^{-10}-2^{-11}-2^{-12})\cdot IN$	0.9924	-0.0660
1 0 0 0 0 0 0	$OUT=(1-2^{-8}-2^{-9}-2^{-10}-2^{-11}-2^{-12}-2^{-13})\cdot IN$	0.9923	-0.0670



Analog Input Invert

Name	Description	Default	D15D14D13D12	D11D10D9D8	D7D6D5D4	D3D2D1D0	Hex Address
invert4_ch<4:1>	Channel specific swapping of the analog input signal for a Quad Channel setup.	IPx is positive input				X X X X	0x24
invert2_ch<2:1>	Channel specific swapping of the analog input signal for a Dual Channel setup.	IPx is positive input			X X		
invert1_ch1	Channel specific swapping of the analog input signal for a 1 channel setup.	IPx is positive input			X		

The IPx pin represents the positive analog input pin, and INx represents the negative (complementary) input. Setting the bits marked *invertx_ch<n:1>* (individual control for each channel) causes the inputs to be swapped. INx would then represent the positive input, and IPx the negative input.

LVDS Test Patterns

Name	Description	Default	D15D14D13D12	D11D10D9D8	D7D6D5D4	D3D2D1D0	Hex Address
en_ramp	Enables a repeating full-scale ramp pattern on the outputs.	Inactive			X 0 0		0x25
dual_custom_pat	Enable the mode wherein the output toggles between two defined codes.	Inactive			0 X 0		
single_custom_pat	Enables the mode wherein the output is a constant specified code.	Inactive			0 0 X		
bits_custom1 <7:0>	Bits for the single custom pattern and for the first code of the dual custom pattern. <0> is the LSB.	0x00	X X X X	X X X X			0x26
bits_custom2 <7:0>	Bits for the second code of the dual custom pattern.	0x00	X X X X	X X X X			0x27
pat_deskew	Enable deskew pattern mode.	Inactive				0 X	0x45
pat_sync	Enable sync pattern mode.	Inactive				X 0	

To ease the LVDS synchronization setup of ASD5010, several test patterns can be set up on the outputs. Normal ADC data are replaced by the test pattern in these modes. Setting *en_ramp* to '1' sets up a repeating full-scale ramp pattern on all data outputs. The ramp starts at code zero and is increased 1LSB every clock cycle. It returns to zero code and starts the ramp again after reaching the full-scale code.

A constant value can be set up on the outputs by setting *single_custom_pat* to '1', and programming the desired value in *bits_custom1<7:0>*. In this mode, *bits_custom1<7:0>* replaces the ADC data at the output, and is controlled by LSB-first and MSB-first modes in the same way as normal ADC data are.

The device may also be made to alternate between two codes by programming *dual_custom_pat* to '1'. The two codes are the contents of *bits_custom1<7:0>* and *bits_custom2<7:0>*.

Two preset patterns can also be selected:

1. Deskew pattern: Set using *pat_deskew*, this mode replaces the ADC output with '01010101'
2. Sync pattern: Set using *pat_sync*, the normal ADC word is replaced by a fixed '11110000' word

Note: Only one of the above patterns should be selected at the same time.



Theory of Operation

ASD5010 is a multi Mode high-speed, CMOS ADC, consisting of 8 ADC branches, configured in different channel modes, using interleaving to achieve high speed sampling. For all practical purposes, the device can be considered to contain 4 ADCs. Fine gain is adjusted for each of the eight branches separately.

ASD5010 utilizes a LVDS output, described in 'Register Description, LVDS Output Configuration and Control'. The clocks needed (FCLK, LCLK) for the LVDS interface are generated by an internal PLL.

The ASD5010 operate from one clock input, which can be differential or single ended. The sampling clocks for each of the four channels are generated from the clock input using a carefully matched clock buffer tree. Internal clock dividers are utilized to control the clock for each ADC during interleaving. The clock tree is controlled by the Mode of operations.

ASD5010 uses internally generated references. The differential reference value is 1V. This results in a differential input of -1V to correspond to the zero code of the ADC, and a differential input of +1V to correspond to the full-scale code (code 255).

The ADC employs a Pipeline converter architecture. Each Pipeline Stage feeds its output data into the digital error correction logic, ensuring excellent differential linearity and no missing codes.

ASD5010 operates from two sets of supplies and grounds. The analog supply and ground set is identified as AVDD and AVSS, while the digital set is identified by DVDD and DVSS.

Interleaving Effects and Sampling Order

Interleaving ADCs will generate interleaving artifacts caused by gain, offset and timing mismatch between the ADC branches. The design of ASD5010 has been optimized to minimize these effects. It is not possible, though, to eliminate mismatch completely, such that additional compensation may be needed, especially when using high digital gain settings. The internal digital fine gain control may be used to compensate for gain errors between the ADC branches. Due to the optimization of ASD5010 there is not a one-to-one correspondence between the sampling order, LVDS outputs and the branch number. Tables 23, 24 and 25 give an overview of the corresponding branches, LVDS outputs and sampling order for the different high speed modes.

Table 23: Quad channel mode

Channel #	Sampling order	LVDS output	Fine gain branch
1	1	D1A	1
	2	D1B	2
2	1	D2A	3
	2	D2B	4
3	1	D3A	5
	2	D3B	6
4	1	D4A	7
	2	D4B	8

Table 24: Dual channel mode

Channel #	Sampling order	LVDS output	Fine gain branch
1	1	D1A	1
	2	D1B	3
	3	D2A	2
	4	D2B	4
2	1	D3A	5
	2	D3B	7
	3	D4A	6
	4	D4B	8

Table 25: Single channel mode

Channel #	Sampling order	LVDS output	Fine gain branch
1	1	D1A	1
	2	D1B	6
	3	D2A	2
	4	D2B	5
	5	D3A	8
	6	D3B	3
	7	D4A	7
	8	D4B	4

Recommended Usage

Analog Input

The analog input to ASD5010 ADC is a switched capacitor track-and-hold amplifier optimized for differential operation.

Operation at common mode voltages at mid supply is recommended even if performance will be good for the ranges specified. The VCM pin provides a voltage suitable as common mode voltage reference. The internal buffer for the VCM voltage can be switched off, and driving capabilities can be changed programming the ext_vcm_bc<1:0> register.

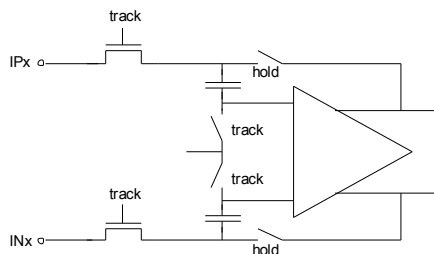


Figure 12: Input configuration

Figure 12 shows a simplified drawing of the input network. The signal source must have sufficiently low output impedance to charge the sampling capacitors within one clock cycle. A small external resistor (e.g. 22 ohm) in series with each input is recommended as it helps reducing transient currents and dampens ringing behavior. A small differential shunt capacitor at the chip



side of the resistors may be used to provide dynamic charging currents and may improve performance. The resistors form a low pass filter with the capacitor, and values must therefore be determined by requirements for the application.

DC-Coupling

Figure 13 shows a recommended configuration for DC-coupling. Note that the common mode input voltage must be controlled according to specified values. Preferably, the CM_EXT output should be used as reference to set the common mode voltage.

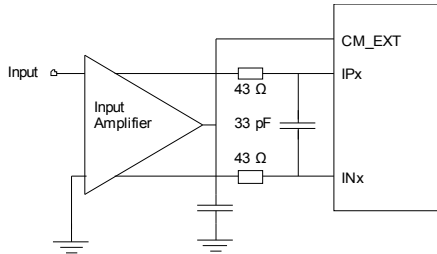


Figure 13: DC coupled input

The input amplifier could be inside a companion chip or it could be a dedicated amplifier. Several suitable single ended to differential driver amplifiers exist in the market. The system designer should make sure the specifications of the selected amplifier is adequate for the total system, and that driving capabilities comply with ASD5010 input specifications.

Detailed configuration and usage instructions must be found in the documentation of the selected driver, and the values given in figure 13 must be adjusted according to the recommendations for the driver.

AC-Coupling

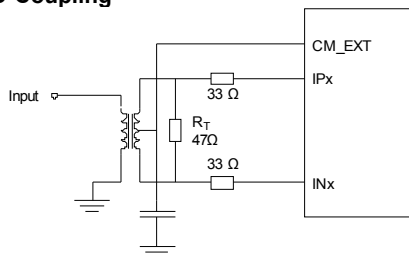


Figure 14: Transformer coupled input

A signal transformer or series capacitors can be used to make an AC-coupled input network. Figure 14 shows a recommended configuration using a transformer. Make sure that a transformer with sufficient linearity is selected, and that the bandwidth of the transformer is appropriate. The bandwidth should preferably exceed the sampling rate of the ADC several times. It is also important to minimize phase mismatch between the differential ADC inputs for good HD2 performance. This type of transformer coupled input is the preferred configuration for high frequency signals as most differential amplifiers do not have adequate performance at high frequencies. Magnetic coupling between the transformers and PCB traces may impact channel crosstalk, and must hence be taken into account during PCB layout.

If the input signal is traveling a long physical distance from the signal source to the transformer (for example a long cable), kick-backs from the ADC will also travel along this distance. If these kick-backs are not terminated properly at the source side, they are reflected and will add to the input signal at the ADC input. This could reduce the ADC performance. To avoid this effect, the source must effectively terminate the ADC kick-backs, or the traveling distance should be very short.

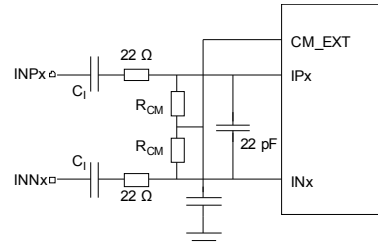


Figure 15: AC coupled input

Figure 15 shows AC-coupling using capacitors. Resistors from the CM_EXT output, R_{CM}, should be used to bias the differential input signals to the correct voltage. The series capacitor, C_i, form the high-pass pole with these resistors, and the values must therefore be determined based on the requirement to the high-pass cut-off frequency.

Note that Start Up Time from Sleep Mode and Power Down Mode will be affected by this filter as the time required to charge the series capacitors is dependent on the filter cut-off frequency.

Clock Input and Jitter Considerations

Typically high-speed ADCs use both clock edges to generate internal timing signals. In ASD5010 only the rising edge of the clock is used.

The input clock can be supplied in a variety of formats. The clock pins are AC-coupled internally, hence a wide common mode voltage range is accepted. Differential clock sources such as LVDS, LVPECL or differential sine wave can be connected directly to the input pins. For CMOS inputs, the CLKN pin should be connected to ground, and the CMOS clock signal should be connected to CLKP. For differential sine wave clock input the amplitude must be at least +/- 0.8 V_{pp}. No additional configuration is needed to set up the clock source format.

The quality of the input clock is extremely important for high-speed, high-resolution ADCs. The contribution to SNR from clock jitter with a full scale signal at a given frequency is shown in equation 1.

$$SNR_{jitter} = 20 \cdot \log(2 \cdot \pi \cdot f_{IN} \cdot \epsilon_t) \quad (1)$$

where f_{IN} is the signal frequency, and ϵ_t is the total rms jitter measured in seconds. The rms jitter is the total of all jitter sources including the clock generation circuitry, clock distribution and internal ADC circuitry.

For applications where jitter may limit the obtainable performance, it is of utmost importance to limit the clock jitter. This can be obtained by using precise and stable clock references (e.g. crystal oscillators with good jitter specifications) and make sure the clock distribution is well controlled. It might be advantageous to use analog power and ground planes to ensure low noise on the supplies to



all circuitry in the clock distribution. It is of utmost importance to avoid crosstalk between the ADC output bits and the clock and between the analog input signal and the clock since such crosstalk often results in harmonic distortion.

The jitter performance is improved with reduced rise and fall times of the input clock. Hence, optimum jitter performance is obtained with LVDS or LVPECL clock with fast edges. CMOS and sine wave clock inputs will result in slightly degraded jitter performance.

If the clock is generated by other circuitry, it should be re-timed with a low jitter master clock as the last operation before it is applied to the ADC clock input.

Application Usage Example

This section gives an overview on how ASD5010 can be used in an application utilizing all active modes with a single clock source. The example assumes that a 1GHz clock source is applied. A differential clock should be used, and can be generated from a single ended crystal oscillator, using a transformer or balun in conjunction with ac-coupling to convert from single ended to differential signal.

Start-up Initialization

The start-up sequence will be as follows:

- Apply power
- Apply reset (RESETN low, then high, or SPI command 0x00 0x0001)
- Set power down (PD pin high or SPI command 0x0F 0x0200)
- Set LVDS bit clock phase (phase_ddr, register 0x42) if other than default must be used (depends on the receiver).
- Select operating mode, for instance dual channel mode, and clock divider factor (SPI command 0x31 0x0102).
- Set active mode (PD pin low or SPI command 0x0F 0x0000)
- Select analog inputs, for instance input 1 on channel 1 and input 3 on channel 2 (SPI commands 0x3A 0202 and 0x3B 0808)

Change Mode

When changing operational mode, power down must be activated due to internal synchronization routines. A typical mode change will then be like this:

- Set power down (PD pin high or SPI command 0x0F 0x0200)
- Change mode to for example Single channel mode (SPI command 0x31 0x0001)
- Set active mode (PD pin low or SPI command 0x0F 0x0000)
- Select analog inputs, for instance Input 1 (SPI commands 0x3A 0202 and 0x3B 0202)

Table 26 gives an overview of the operational modes in this example and the SPI commands to apply for each mode.

Table 26: Overview of operating modes and setup conditions

Operating mode	Sampling speed [MSPS]	Clock divider factor	SPI command for mode selection and clock divider
Single channel	1000	1	0x31 0x0001
Dual channel	500	2	0x31 0x0102
Quad channel	250	4	0x31 0x0204

Select Analog Input

When an operational mode is selected, the analog inputs can be changed 'on-the-fly'. To change analog input one merely have to apply the dedicated SPI commands. The change will occur instantaneously at the end of each SPI command.

Table 27: Example of some analog input selections

Operating mode	Signal input selection	SPI commands
Single channel	IP4/IN4	0x3A 1010, 0x3B 1010
Dual channel	Ch1: IP2/IN2 Ch2: IP3/IN3	0x3A 0404, 0x3B 0808
Quad channel	Ch1: IP4/IN4 Ch2: IP3/IN3 Ch3: IP2/IN2 Ch4: IP1/IN1	0x3A 1008, 0x3B 0402



Package Mechanical Data

QFN48

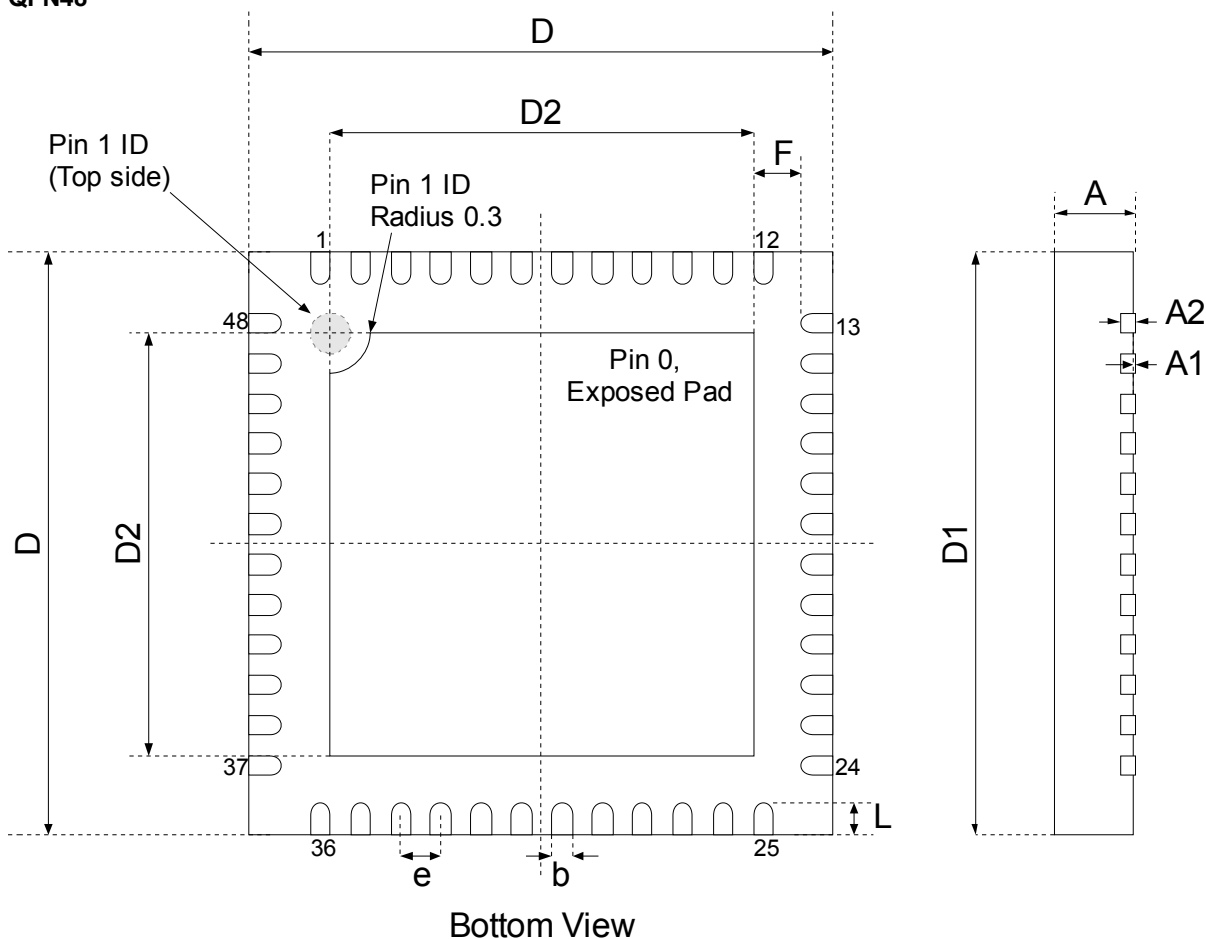


Table 28: QFN48 Dimensions

Symbol	Millimeter			Inch		
	Min	Typ	Max	Min	Typ	Max
A	0.8	0.9	1.0	0.031	0.035	0.039
A1	0.00	0.02	0.05	0.000	0.0008	0.002
A2		0.2			0.008	
b	0.18	0.25	0.3	0.007	0.010	0.012
D		7.00 bsc			0.276 bsc	
D2	5.15	5.3	5.4	0.203	0.209	0.213
L	0.3	0.4	0.5	0.012	0.016	0.020
e		0.50 bsc			0.020 bsc	
F	0.6			0.024		



Product Information

Product	Status	Datasheet revision	Date
ASD5010	Preliminary Product Specification	2.0	2010.11.08

Ordering information

Model	Temp. range	Package type	Package drawing	MSL, Peak temp (1)	Transport Media
ASD5010L500INT	-40 to +85 °C	48 pin QFN	QFN48	Level 2A	Tray
ASD5010L1000INT	-40 to +85 °C	48 pin QFN	QFN48	Level 2A	Tray

(1) MSL, Peak Temp: The moisture sensitivity level rating classified according to the JEDEC industry standard and to peak solder temperature.

Datasheet status

Objective Product Specification:

The values and functionality describe design targets only. Specifications and functionality can be changed without notice.

Preliminary Product Specification:

The specifications are based on initial design results. Specifications and functionality can be changed without notice.

Product Specification:

Information is current as of publication data. Products conform to specifications according to the terms of Arctic Silicon Devices AS standard warranty. Production does not necessarily require all parameters to be tested.



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